SPECIFICATION FOR APPROVAL

1/32W, 01005 Low Resistance Chip Resistor (Lead / Halogen free)

1. Scope

This specification applies 0.2mm x 0.4mm (01005) size 1/32W, fixed metal film chip resistors rectangular type for use in electronic equipment.

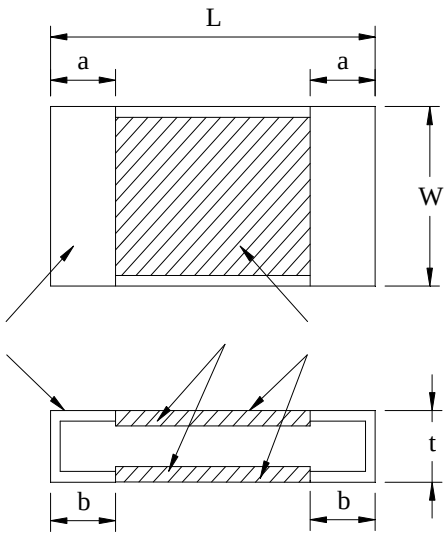
2. Type Designation

RL 0204 — G — □□□□ □

(1) (2) (3) (4)

Where
(1) Series No.
(2) Power rating
G = 1/32W
(3) Resistance value:
For example—
R300 = 0.3 Ω
(4) Resistance tolerance:
F= ± 1%
G= ± 2%
J= ± 5%

3. Construction and Physical Dimensions



Code Letter	Dimensions (mm)
L	0.40 ± 0.03
W	0.21 ± 0.03
t	0.14 ± 0.03
a	0.10 ± 0.03
b	0.10 ± 0.03

NOTE:
① Resistive element
(under protection film)
② Electrode
③ Protection film
(up side:white color; down side:black color)
④ Substrate

Figure 1. Structure (No mark)

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4. Ratings

4-1 Specification

Power Rating*	1/32 W
Resistance Range	0.3Ω ~ 1.0Ω
Temperature Coefficient of Resistance	±200ppm/℃
Resistance Tolerance	±1% , ±2% , ±5%

Note*:

Power Rating is based on continuous full load operation at rated ambient temperature of 70℃. For resistors operated at ambient temperature in excess of 70℃, the maximum load shall be derated in accordance with the following curve.

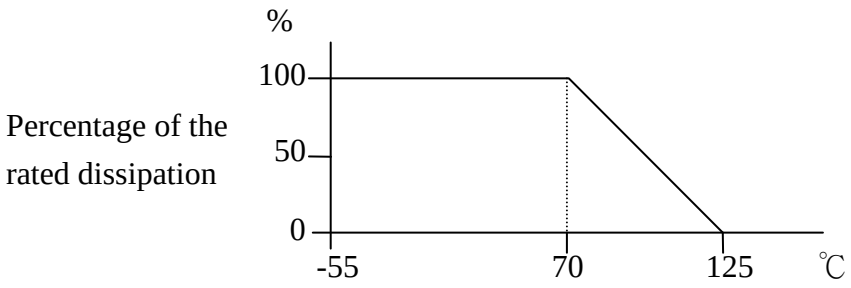

Figure 2 Derating Curve

4-2 Rated Voltage

The rated voltage shall be determined by the following expression.

$V = \sqrt{P \times R}$ Where V：Rated voltage (V)

R：Nominal resistance value (Ω)

P：Rated dissipation (W)

4-3 Operating and Storage Temperature Range

-55 to +125℃

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5. Characteristics

Test Item	Condition of Test	Requirements
Short Time Overload	2.5 * Rated power for 5 seconds Refer to JIS C 5201-1 4.13	ΔR : ± (2.0%+0.0005Ω) Without significant damage by flashover (spark, arching), burning or breakdown etc.
Insulation Resistance	The resistor shall be cramped in the metal block and tested , as shown below. Test voltage : 100 ± 15V_{DC} for 1 minute Refer to JIS C 5201-1 4.6 Mounting condition G.	Between Electrode and Protection Film 100MΩ or over Between Electrode and Substrate 1,000MΩ or over
Voltage Proof	The voltage : 100V_{AC} (rms.) for 1 minute Refer to JIS C 5201-1 4.7	ΔR : ± (2.0%+0.0005Ω) Without damage by flashover, fire or breakdown, as shown below.
Thermal Shock	-55 ~125℃ 5 cycles, 15 min at each extreme condition Refer to JIS C 5201-1 4.19	ΔR : ± (1.0%+0.0005Ω) Without distinct damage in appearance
Low Temperature Storage	Kept at -55℃, 1,000 hours Refer to JIS C 5201-1 4.23.4	ΔR : ± (5.0%+0.0005Ω) Without distinct damage in appearance
High Temperature Exposure	Kept at 125℃ for 1,000 hours Refer to JIS C 5201-1 4.23.2	ΔR : ± (5.0%+0.0005Ω) Without distinct damage in appearance
Solderability	Temperature of Solder : 245 ± 5℃ Immersion Duration : 2 ± 0.5 second Refer to JIS C 5201-1 4.17	Uniform coating of solder cover minimum of 95% surface being immersed
Resistance to Soldering Heat	Dipped into solder at 270 ± 5℃ for 10 ± 1 seconds Refer to JIS C 5201-1 4.18	ΔR : ± (1.0%+0.0005Ω) Without distinct deformation in appearance

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Test Item	Condition of Test	Requirements
Load Life	Rated voltage for 1.5 hours followed by a pause 0.5 hour at 70 ± 2℃. Cycle repeated 1000 hours Refer to JIS C 5201-1 4.25	ΔR : ± (5.0%+0.0005Ω) Without distinct damage in appearance
Damp Heat with Load	40 ± 2℃ with relative humidity 90% to 95%. D.C. rated voltage for 1.5 hours ON and 30 minutes OFF. Cycle repeated 1,000 hours Refer to JIS C 5201-1 4.24	ΔR : ± (5.0%+0.0005Ω) Without distinct damage in appearance
Mechanical Shock	100 G's for 6milliseconds. 5 pulses Refer to JIS C 5201-1 4.21	ΔR : ± (0.5%+0.0005Ω) Without mechanical damage such as break
Bending Test	Glass-Epoxy board thickness : 1.6mm Bending width : 2mm Between the fulcrums : 90mm Refer to JIS C 5201-1 4.33	ΔR : ±(1.0%+0.0005Ω) Without mechanical damage such as break

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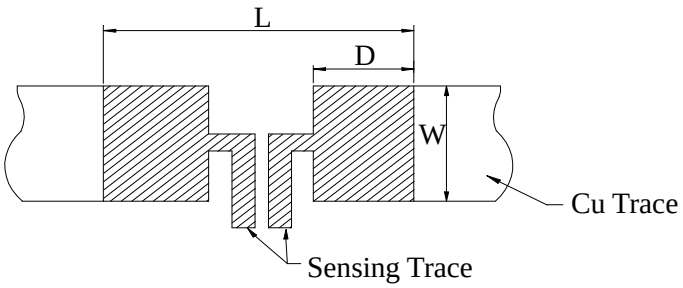
6. Recommended Solder Pad Dimensions

	W	L	D
0204	0.2~0.4	0.5~0.8	0.17~0.3

Unit : mm



Note : We recommend there is no circuit design between pads to avoid circuit short

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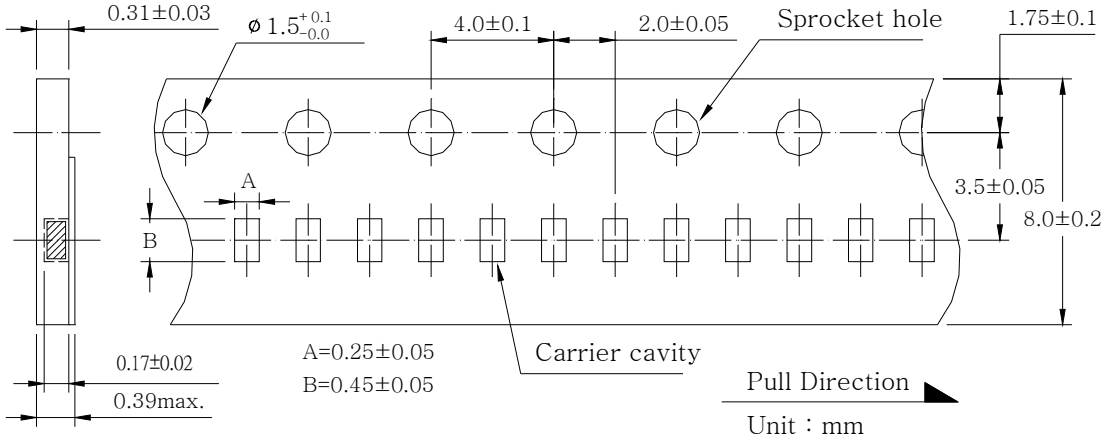
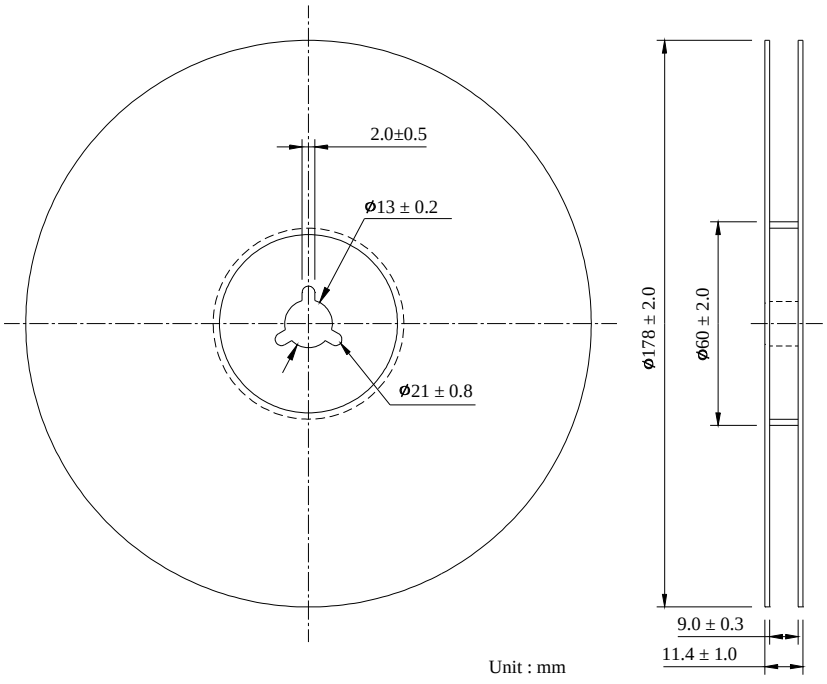
7. Packaging

7-1 Dimensions

7-1-1 Tape packaging dimensions



7-1-2 Reel dimensions



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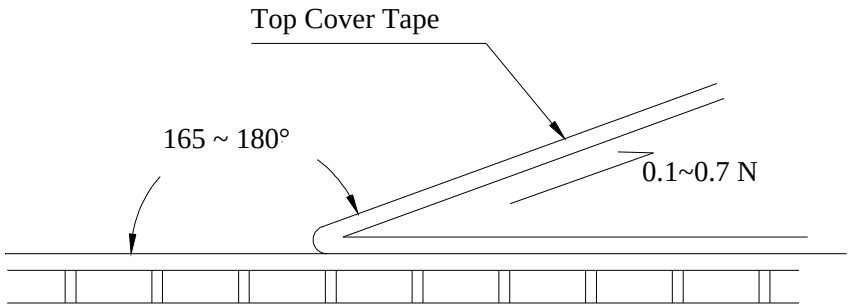
7-2 Peel force of top cover tape

The peel speed shall be about 300 mm/min.

The peel force of top cover tape shall be between 0.1 to 0.5 N.



7-3 Numbers of taping

20,000 pieces /reel

7-4 Making

The following items shall be marked on the reel.

(1) Type designation.

(2) Quantity

(3) Manufacturing date code

(4) Manufacturer’s name